Rev. A2

1

SMC490

- SMD LED
- 490 nm, 6.8 mW
- Chip: InGaN, 350 x 350 μm, 1 pc.
- SMD package, Ceramic, 3.0 x 2.0 x 1.1 mm
- Viewing Angle: 128°





Description

SMC490 is a surface mount InGaN LED with a typical peak wavelength of **490 nm** and radiation of **6.8 mW**. It comes in SMD package (ceramic) and is sealed with silicone or epoxy resin.

Maximum Ratings (TCASE=25°C)

B	Ohl	Val	11-26		
Parameter	Symbol	Min.	Max.	Unit	
Power Dissipation	P_D		220	mW	
Forward Current	I _F		50	mA	
Pulse Forward Current *1	I FP		100	mA	
Reverse Voltage	VF		5	V	
Thermal Resistance	R _{THJA}		80	K/W	
Junction Temperature	T_J		120	°C	
Operating Temperature	T_{CASE}	- 40	+ 100	°C	
Storage Temperature	T _{STG}	- 40	+ 100	°C	
Lead Solder Temperature *2	T_{SLD}		+ 250	°C	

^{*1} duty=1%, pulse width = 10 μ s

Electro-Optical Characteristics (TCASE=25°C)

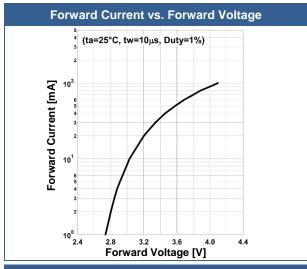
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	λ_P	I _F =20mA	480		500	nm
Dominant Wavelength	λ_D	I _F =20mA		492		nm
Half Width	$\Delta \lambda$	I _F =20mA		32		nm
Forward Voltage	VF	I _F =20mA		3.2	4.3	V
		I _{FP} =100mA		4.1		V
Radiated Power *	Po	I _F =20mA	4.7	6.8		mW
		I _{FP} =100mA		23		IIIVV
Dadient Intensity	lE	I _F =20mA		2.2		m2\/\/o.r
adiant Intensity		I _{FP} =100mA		7.6		mW/sr
Luminous Flux	ΦV	I _F =20mA		1700		mlm
Viewing Angle	φ	I _F =20mA		128		deg.
Rise Time	t r	I _F =20mA		35		ns
Fall Time	t f	I _F =20mA		40		ns

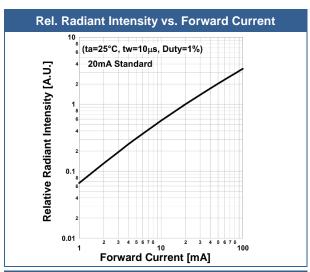
^{*1} measured by S3584-08

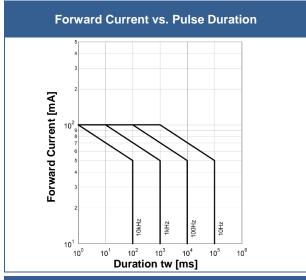
^{*2} must be completed within 3 seconds

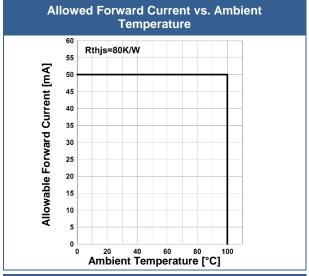
^{*2} measured by CIE127-2007 Condition B

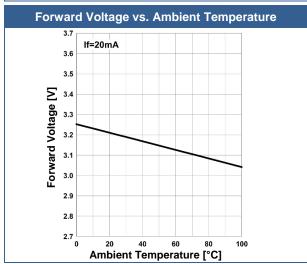
Typical Performance Curves

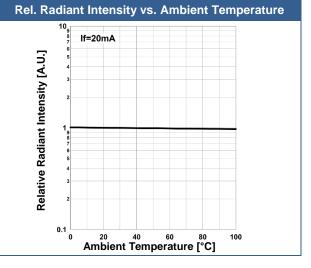










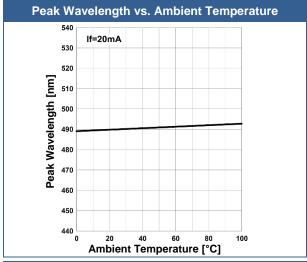


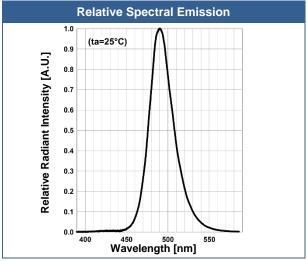


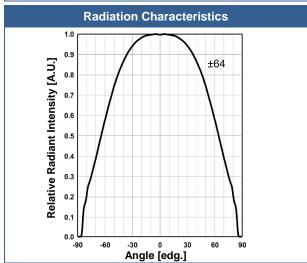
ROITHNER LASERTECHNIK GmbH

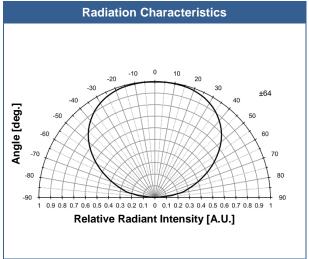
WIEDNER HAUPTSTRASSE 76 IO40 VIENNA AUSTRIA TEL. +43 I 586 52 43 -0, FAX. -44 OFFICE@ROITHNER-LASER.COM



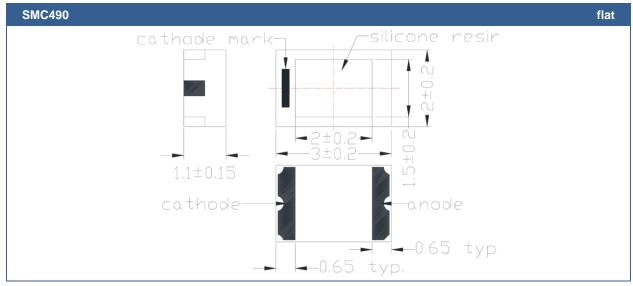








Outline Dimensions



All Dimensions in mm

Precautions

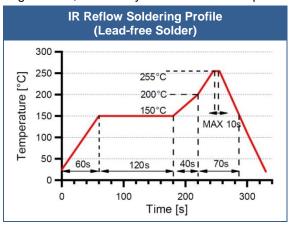
Soldering:

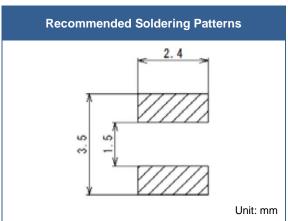
- · Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering

Recommended soldering conditions:

This LED is designed to be reflow soldered on to a PCB. If dip soldered or hand soldered, its reliability cannot be guarantee.

Nitrogen reflow soldering is recommended. Air flow soldering conditions can cause optical degradation, caused by heat and/or atmosphere.





Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

Static Electricity:

LEDs are sensitive to electrostatic discharge (ESD). Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

Radiation:

Those LEDs do emit **invisible light**, which is invisible and may cause cancer. Do avoid exposure to the emitted light. It is further advised to attach a warning label on products/systems.

Operation:

Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device.

Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

Revisions History

Rel.	Rel. Date	Chapter	Modification	Page
A2	2022-05-01	-	Initial release	-

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